

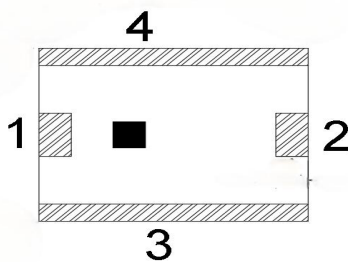
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

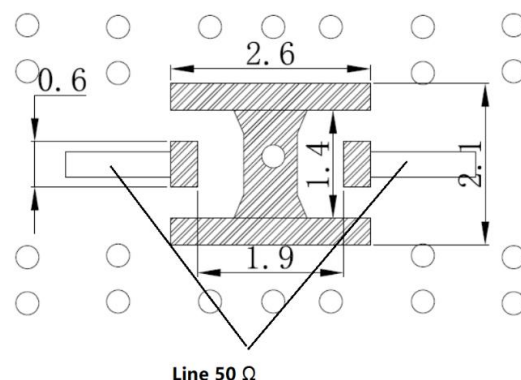
NO.	Parameter	SPC
1	Frequency (MHz)	2400~2500
2	Insertion Loss (dB)@25°C	≤1.2
3	Ripple (dB)	≤0.6
4	VSWR(In BW)	≤2.0
5	Attenuation	≥30dB@880~1785MHz
		≥35dB@1850~1910MHz
		≥25dB@4800~5000MHz
		≥22dB@7200~7500MHz
6	In/Output Impedance (Ω)	50
Operating & Storage Condition (Component)		
Operation Temperature Range: -55°C ~ +85°C		
Storage Temperature Range: -55°C~ +85°C		
Storage Condition before Soldering (Included packaging material)		
Storage Temperature Range: +5 ~ +40 °C		
Humidity: 30 to 70% relative humidity		

Construction



PIN	Connection	PIN	Connection
1	input Port	2	output Port
3	GND	4	GND

Mounting Considerations



Unit: mm

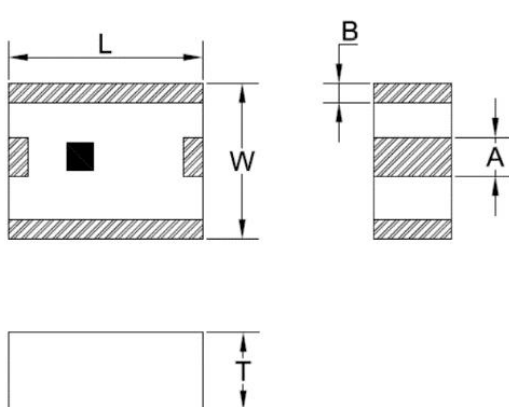
Yantel Corporation

Add: No.308-322,3F,Building 1,Juchuang Jingu Innovation Park,Wenyuan Road 35,Xili Street,Nanshan,Shenzhen,China

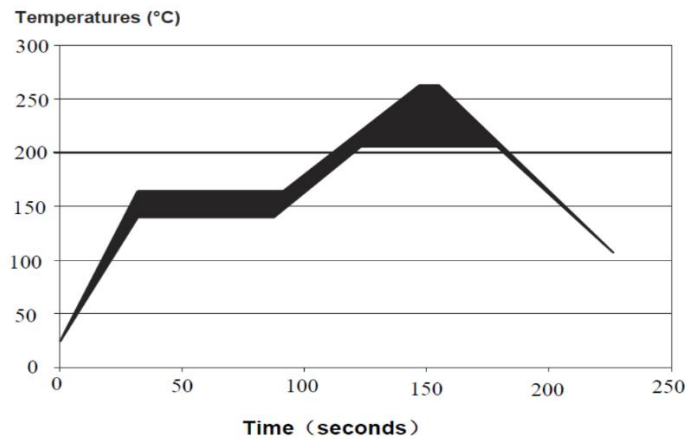
Tel: 86-755-8355-1886 Fax: 86-755-8355-2533

For detailed performance specs & shopping online see Yantel web site : www.yantel-corp.com

Dimensions

Figure	Symbol	Dimension (mm)
	L	2.50±0.20
	W	2.0±0.20
	T	1.0±0.20
	A	0.50±0.10
	B	0.20±0.10

Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.